



PROPOSED STACK-UP

Texas Instruments

TRF3703 Rev A (Impedance Model)

<u>Overall Thickness =</u>		.062	+/- .006		Polyclad 370 HR (Lead Free Assembly) Er (Dielectric Constant) = 4.3		
	<u>Dielectric</u>		<u>Copper</u>		<u>Target Impedance</u>	<u>Line Width</u>	<u>Calc</u>
1	----- .011	Signal	1.5 oz	50 ohms +/- 10%	.018	50.3	
2	----- <div style="border: 1px solid black; padding: 2px;">.033</div>	Plane	1 oz				
3	----- .011	Plane	1 oz				
4	-----	Plane	1.5 oz				
	.062	Final Thickness (After Plating)					

James Rader
Inside Sales Engineer
(714) 974-8590 x1749

Important:

- 1) Approval of this stack-up supersedes fabrication drawing requirements.
- 2) Some laminates require special order and additional lead time.
Please check with MEI sales personnel and verify material availability.